

E1100S™

Heat-Curing Epoxy Adhesive

for

Pull-off and Tensile Adhesion Testing

- **USER INSTRUCTIONS**
- **SAFETY DATA SHEET**

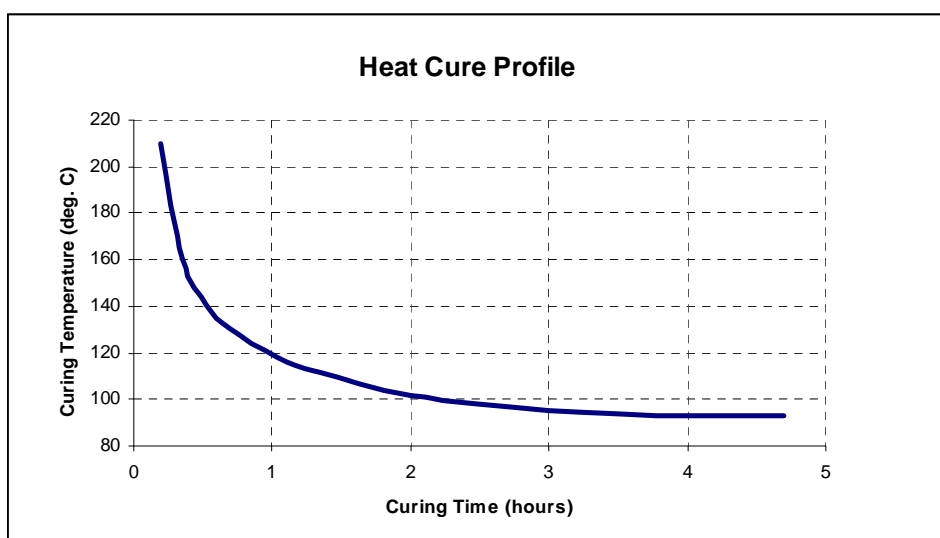
Unlike conventional epoxies this resin and hardener are already mixed in a single part, with the adhesive formulated to cure rapidly as soon as the temperature is raised.

Typical methods of heat cure

- Oven
- Hot Air
- Hot Plate
- Induction
- Infra Red

Energy in the form of heat is required to convert the paste into the final form. Rapid assembly is achieved by selecting temperature towards the top end of the curing profile chart.

Total curing time



Minimum curing time at varying temperatures

Note that the curing time in the diagram is for the actual adhesive to cure. The time taken to warm up the components to be bonded must be taken into consideration. The larger the components the longer the warm-up time. The warm-up time will also depend on which heating method is used.

Example: If curing at 200°C for 15 minutes (from the chart) is desirable, the warm up time of the test element assembly (in a typical oven) could be considerably longer and must be added to the curing time in the graph.

Storage and shelf life

In order to maximise the shelf life of E1100S unopened syringes should be stored in a deep freezer. Once in regular use the adhesive should be stored refrigerated. Continuous thawing and re-freezing will reduce the overall shelf life.